

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

B110WS

Product specification



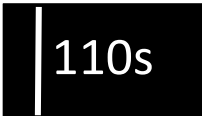
FEATURES

- Guard ring protection.
- Low forward voltage drop.
- For use in low voltage, high frequency inverters .
- High surge current capability.

APPLICATIONS

- Low voltage rectification
- Reverse polarity protection
- Low power consumption applications

Reference News

PACKAGE OUTLINE	Circuit	Marking
		
SOD-323		

Absolute Maximum Ratings(Ta=25℃)

Symbol	Parameter	Limit	Unit
V _{RRM}	Maximum Recurrent Peak Reverse Voltage	100	V
V _{RMS}	Maximum RMS Voltage	70	V
V _{DC}	Maximum DC Blocking Voltage	100	V
I _F	Continuous Forward Current	1	A
I _{FSM}	Non-repetitive Peak Forward Surge Current@8.3mS	25	A
P _{tot}	Total Power Dissipation	250	W
R _{θJA}	Thermal Resistance From Junction To Ambient	400	℃/W
T _J	Operation Junction Temperature Range	-40~+ 125	℃
T _{STG}	Storage Temperature Range	-55~+ 150	℃

Electrical Characteristics (Ta=25℃ unless otherwise specified)

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
V _F	Forward voltage(1)	I _F =1A			0.85	V
I _R	Reverse voltage leakage current	V _R =100V		0.5	2.0	A

Typical Characteristics

Fig.1 Forward Current Derating Curve

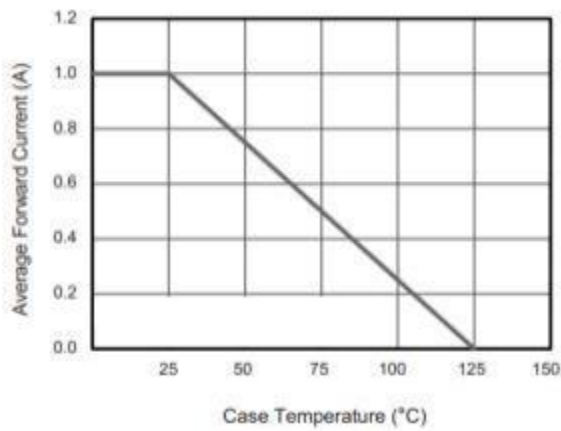


Fig.2 Typical Reverse Characteristics

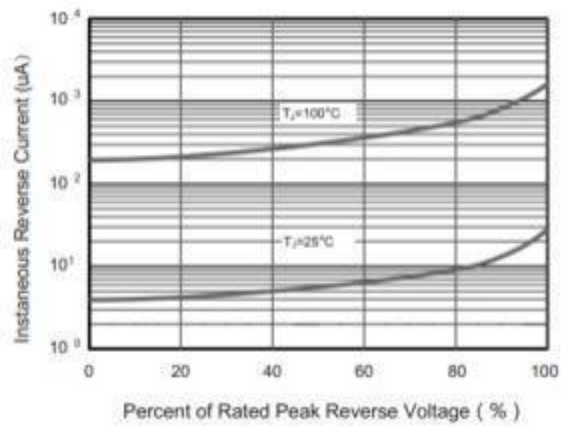
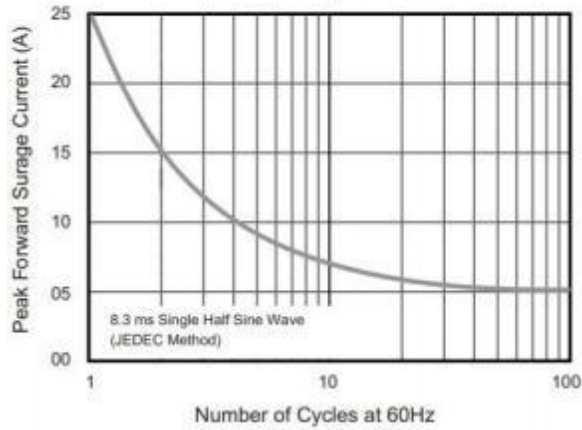
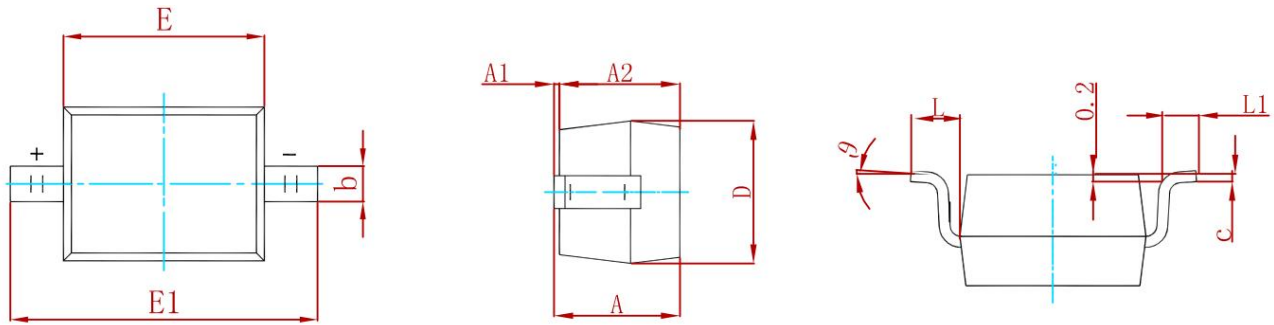
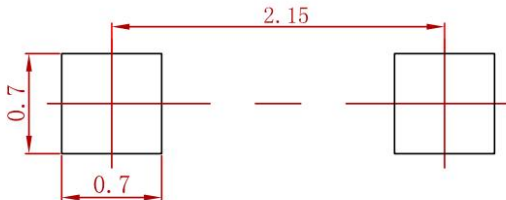


Fig.3 Maximum Non-Repetitive Peak Forward Surge Current



PACKAGE MECHANICAL DATA


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
e	0°	8°	0°	8°

Suggested Pad Layout

Note:

1. Controlling dimension; in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
B110WS	SOD-323	3000

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